

WHAT IS CLAIMED IS:

1. A polishing member providing a polishing surface which exerts a polishing action by slidable engagement with a substrate to be polished, wherein one or more spiral grooves are formed in the polishing surface so as to extend from a central portion to an outer peripheral edge of the polishing surface.

2. The polishing member according to claim 1, wherein the spiral grooves extend in spiral form in one direction.

3. The polishing member according to claim 1, wherein the spiral grooves comprise one or more first spiral grooves extending in spiral form in one direction and one or more second spiral grooves extending in spiral form in a direction opposite to the direction of extension of the first spiral grooves.

4. The polishing member according claim 1, wherein a spiral angle of each spiral groove is 90° to 450° , the spiral angle being defined as an angle formed by a line connecting the center of the polishing surface and a starting point of the groove and a line connecting the center of the polishing surface and an end point of the groove, as measured in the direction of extension of the groove.

5. The polishing member according to claim 2, wherein a spiral angle of each spiral groove is 90° to 450° , the spiral angle being defined as an angle formed by a line connecting the center of the polishing surface and a starting point of the groove and a line connecting the

center of the polishing surface and an end point of the groove, as measured in the direction of extension of the groove.

6. The polishing member according to claim 3, wherein a spiral angle of each spiral groove is 90° to 450° , the spiral angle being defined as an angle formed by a line connecting the center of the polishing surface and a starting point of the groove and a line connecting the center of the polishing surface and an end point of the groove, as measured in the direction of extension of the groove.

7. The polishing member according to claim 2, wherein the polishing member comprises one member selected from a polishing pad and an abrasive plate.

8. The polishing member according to claim 3, wherein the polishing member comprises one member selected from a polishing pad and an abrasive plate.

9. The polishing member according to claim 4, wherein the polishing member comprises one member selected from a polishing pad and an abrasive plate.

10. The polishing member according to claim 5, wherein the polishing member comprises one member selected from a polishing pad and an abrasive plate.

11. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 1 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

12. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 2 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

13. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 3 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

14. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 4 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

15. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 5 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

16. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 6 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

17. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 7 and a substrate holder adapted to hold the substrate to be

polished and press the substrate against the polishing surface of the polishing member on the polishing table.

18. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 8 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

19. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 9 and a wafer holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.

20. A polishing apparatus comprising a polishing table having attached thereto a polishing member of claim 10 and a substrate holder adapted to hold the substrate to be polished and press the substrate against the polishing surface of the polishing member on the polishing table.